COMPLIANT

HALOGEN FREE Available



Dual N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
	V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)			
Channel-1	20	0.019 at $V_{GS} = 10 \text{ V}$	8.0			
		0.026 at V _{GS} = 4.5 V	6.9			
Channel-2	30	0.035 at V _{GS} = 10 V	6.0			
		0.048 at V _{GS} = 4.5 V	5.0			

SO-8 D_1 D_2 D_2

Top View

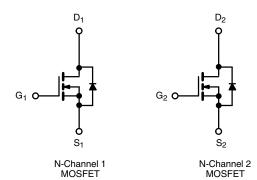
Ordering Information: Si4974DY-T1-E3 (Lead (Pb)-free) Si4974DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFETs
- 100 % R_g Tested

APPLICATIONS

- Logic DC/DC
 - Notebook PC



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted								
			Channel-1		Channel-2		Unit	
Parameter	Symbol	10 s	Steady State	10 s	Steady State	Onit		
Drain-Source Voltage	V _{DS}	30				V		
Gate-Source Voltage		V _{GS}	± 20				V	
Continuous Dusin Courset /T 450 90\8	T _A = 25 °C	- I _D	8.0	6.0	6.0	4.4		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		6.5	4.7	4.8	3.5]	
Pulsed Drain Current		I _{DM}		40	30		Α	
Continuous Source Current (Diode Conduction) ^a		I _S	1.8	1.0	1.8	1.0		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}		15	7			
Avalanche Energy		E _{AS}		11		2.45	mJ	
Maximum Power Dissipation ^a	T _A = 25 °C	P _D	2	1.1	2	1.1	W	
	T _A = 70 °C	'D	1.3	0.7	1.3	0.7	VV	
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150				°C		

THERMAL RESISTANCE RATINGS								
		Chan	nel-1	Channel-2		Limit		
Parameter		Symbol	Тур.	Max.	Тур.	Max.	Unit	
Maximum Junction-to-Ambient ^a	t ≤ 10 s	R _{thJA}	50	62.5	52	62.5		
	Steady State	ithJA	90	110	91	110	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	30	40	32	40		

a. Surface Mounted on 1" x 1" FR4 board.



Parameter	Symbol	_J = 25 °C, unless otherwise noted			Typ.a	Max.	Unit	
Static	- Jz	1000 001121110110		Min.	-3/6-		-	
	V _{GS(th)}	., .,	Ch-1	1.0		3.0		
Gate Threshold Voltage		$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	Ch-2	1.0		3.0	V	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	Ch-1			± 100	- nA	
			Ch-2			± 100		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	Ch-1			1		
			Ch-2			1	μΑ	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$	Ch-1			15	μπ	
			Ch-2			15		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	Ch-1	20			Α	
		V _{GS} = 10 V, I _D = 8.0 A	Ch-2	20	0.010	0.010	 	
			Ch-1		0.016	0.019	Ω	
Drain-Source On-State Resistance ^b	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 6.0 \text{ A}$	Ch-2		0.029	0.035		
Dialit-Source Oil-State nesistance	DO(OII)	$V_{GS} = 4.5 \text{ V}, I_D = 6.9 \text{ A}$	Ch-1		0.0215	0.026		
		$V_{GS} = 4.5 \text{ V}, I_D = 5.0 \text{ A}$	Ch-2		0.040	0.048		
Forward Transconductance ^b	g _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 8.0 \text{ A}$	Ch-1		19		S	
Torward Transconductance		$V_{DS} = 15 \text{ V}, I_{D} = 6.0 \text{ A}$	Ch-2		13			
Diada Farmani Valla nah	V _{SD}	$I_S = 1.8 \text{ A}, V_{GS} = 0 \text{ V}$	Ch-1		0.8	1.1	V	
Diode Forward Voltage ^b		I _S = 1.8 A, V _{GS} = 0 V	Ch-2		0.8	1.1	1 V	
Dynamic ^a								
Total Gate Charge	Qg	Channel-1 V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 8.0 A	Ch-1		7.0	11	nC	
Total Gate Charge			Ch-2		3.3	5		
Gate-Source Charge	Q_{gs}	$V_{DS} = 13 \text{ V}, V_{GS} = 4.3 \text{ V}, I_D = 8.0 \text{ A}$	Ch-1		2.6			
date course charge		Channel-2	Ch-2		1.2			
Gate-Drain Charge	Q _{gd}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 6.0 \text{ A}$	Ch-1		3.0			
			Ch-2		1.5			
Gate Resistance	R _g		Ch-1	0.8	1.5	2.3	Ω	
			Ch-2	0.9	1.95	2.9		
Turn-On Delay Time	t _{d(on)}	Channel-1 $V_{DD} = 15 \text{ V, R}_{L} = 15 \Omega$	Ch-1		8	15		
			Ch-2		6	10	- - ns	
Rise Time		$I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 6 \Omega$	Ch-1		12	20		
		D = 17, TGEN 10 1, TG = 322	Ch-2		11	18		
Turn-Off Delay Time	t _{d(off)}	Channel-2	Ch-1		22	35		
•		$V_{DD} = 15 \text{ V}, R_L = 15 \Omega$	Ch-2		15	25		
Fall Time		$I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 6 \Omega$	Ch-1		6	10		
	· .		Ch-2 Ch-1		6	10		
Source-Drain Reverse Recovery Time	t _{rr}	rr I _F = 1.8 A, dI/dt = 100 A/μs			20	40		
,	.,		Ch-2		15	30		

Notes:

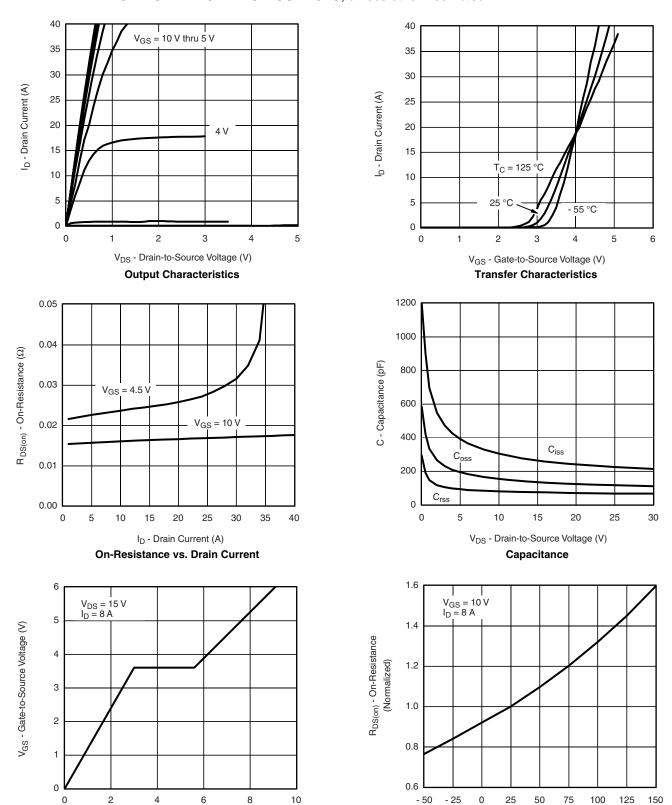
- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Q_q - Total Gate Charge (nC)

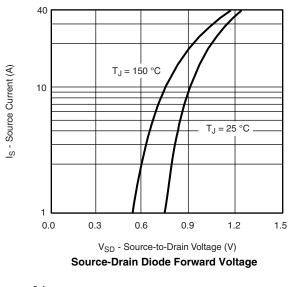
Gate Charge

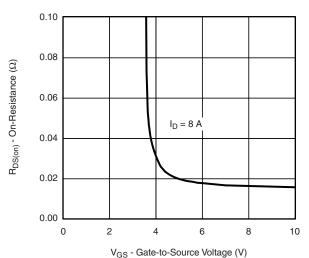
T_J - Junction Temperature (°C)

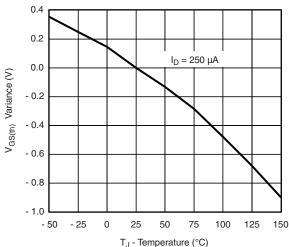
On-Resistance vs. Junction Temperature

VISHAY

CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

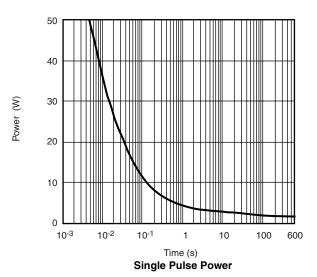


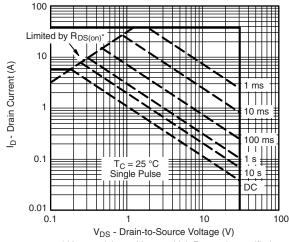




Threshold Voltage

On-Resistance vs. Gate-to-Source Voltage



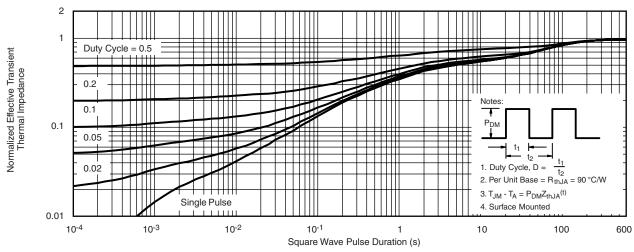


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

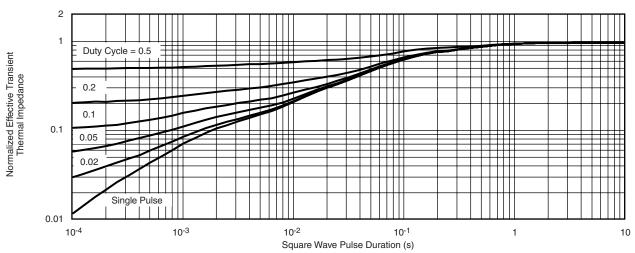
Safe Operating Area, Junction-to-Case



CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



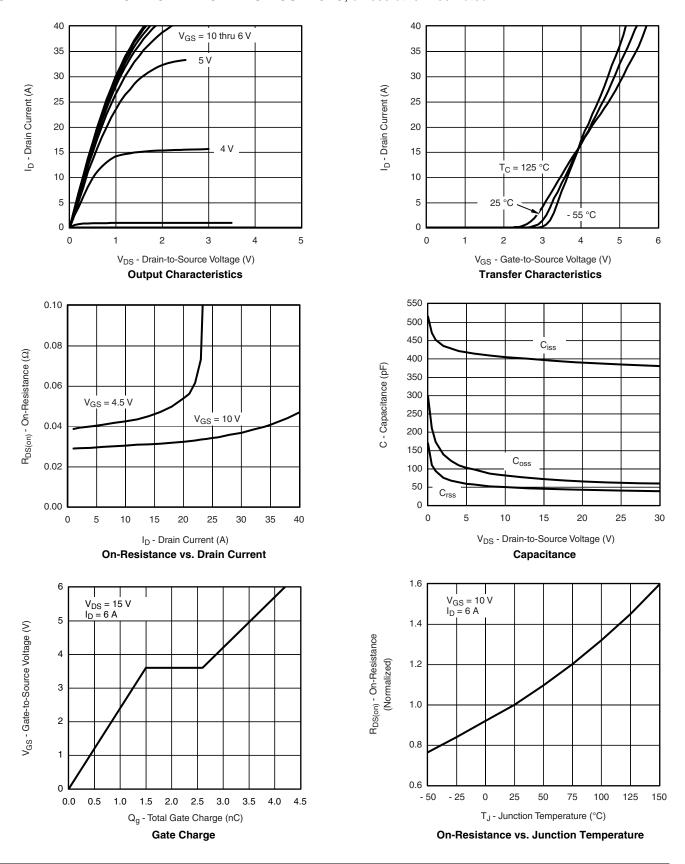
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

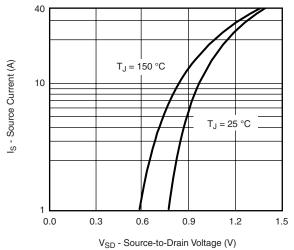


CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

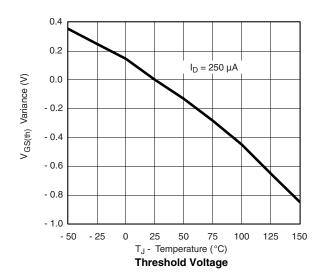


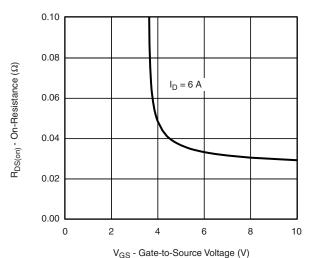


CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

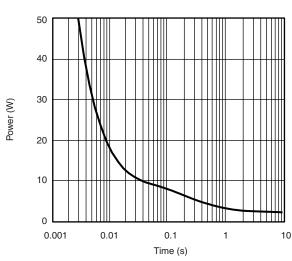


Source-Drain Diode Forward Voltage

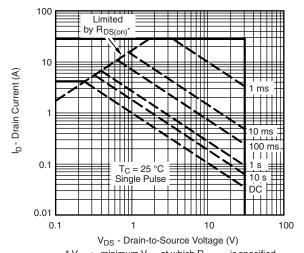




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

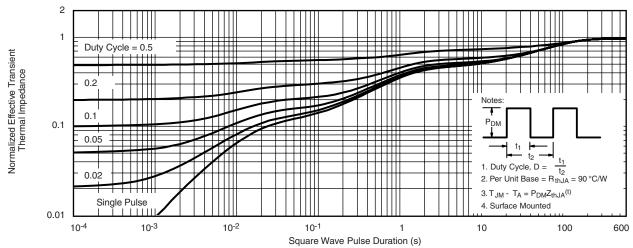


 * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

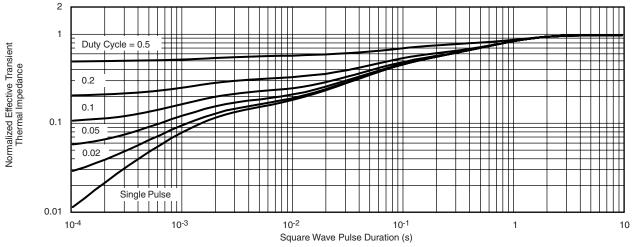
Safe Operating Area, Junction-to-Case



CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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